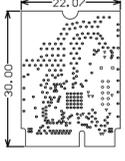


Symbol	Quantity	Finished Hole Size	Plated	Hole Type	Drill Layer Pair	Hole Tolerance
∇	13	7.87mil (0.200mm)	PTH	Round	Top Layer - Bottom Layer	
⊕	263	8.50mil (0.215mm)	PTH	Round	Top Layer - Bottom Layer	
⊖	10	27.95mil (0.710mm)	PTH	Round	Top Layer - Bottom Layer	
□	2	45.28mil (1.150mm)	PTH	Round	Top Layer - Bottom Layer	
288 Total						

Layer	Name	Material	Thickness	Constant	Board Layer Stack
	Top Overlay				
	Top Solder	Solder Resist	1.00mil	3,5	
1	Top Layer		1.85mil		
	Dielectric 1	FR-4 High Tg	5.48mil	4,2	
2	LD2_SND		1.26mil		
	Dielectric1	FR-4 High Tg	12.32mil	4,2	
3	LD3_PtR		1.26mil		
	Dielectric 2	FR-4 High Tg	5.48mil	4,2	
4	Bottom Layer		1.85mil		
	Bottom Solder	Solder Resist	1.00mil	3,5	
	Bottom Overlay				



IMPEDANCE TABLE:

LAYER	50 OHM CPW (Z0)
LO1_TOP	10.29MIL/15 MIL
LO4_BOTTOM	---

TOLERANCE : +/-10%

ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #:MCU127	REV: A	SUN REV: acc4e9a24df3bc4f1063ba3ba651eb3e15 (Locality Modified)
LAYER NAME = PCB Fabrication	TID #: N/A		
PLOT NAME = Fabrication Drawing	GENERATED 3/21/2024 2:19:13 PM	TEXAS INSTRUMENTS	



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ENGINEER: Jessica M. Torres

SCALE: 1.00

LAYOUT BY: Jessica M. Torres

ALTIM DESIGNER VERSION: 24.2.2.26

DESIGN INFORMATION

MIN. TRACK WIDTH: 4 MIL
 MIN. CLEARANCE: 4 MIL
 MIN. VIA PAD SIZE: 14 MIL
 MINIMUM ANNULAR RING: 0.05mm (2MIL) EXTERNAL
 PER IPC-D-275 CLASS 2 LEVEL C
 REGISTRATION TOLERANCES: METAL +/- 5 MIL HOLES +/- 3 MIL
 HOLE SIZE TOLERANCE (UNLESS OTHERWISE SPECIFIED): +/- 3 MIL

MATERIAL:
 FR-4 FR-4 High Tg OTHER

THICKNESS: 31.5 MIL (0.8mm) +/-10% OTHER

TOLERANCE: ANSI IPC-6012 TYPE 3 CLASS 2
 OTHER +/-

BOW & TWIST: ANSI IPC-6012 TYPE 3 CLASS 2
 OTHER +/-

DRILLING:
 REFERENCE: AS SHOWN NO DRILL FILES
 PTH COPPER THICKNESS: 20-30 um OTHER

BOARD FINISH:
 SILKSCREEN: TOP BOTTOM
 SILKSCREEN COLOR: WHITE OTHER
 SOLDER RESIST COLOR: GREEN OTHER RED
 MATTE SEM-GLOSS

SURFACE FINISH: IMMERSION GOLD (ENIG) ENEPG
 MM. TIN/SILVER OR EQUIV OTHER

ARRAY/PANEL: CUT AND TRM PER M1 BOARD OUTLINE
 N.C. ROUTE V. SCORE

CERTIFICATION: MATERIALS AND WORKMANSHIP FOR ALL PCBs TO MEET OR EXCEED THE REQUIREMENTS OF:
 ANSI IPC-A-600F CLASS -> 1 2 3
 RoHS OTHER PER ORDER

ALL BOARDS MUST MEET OR EXCEED UL94-V0 REQUIREMENTS.
 PCB MUST BEAR THE UL94-V0 UL REGISTERED MATERIAL ID NUMBER

ADDITIONAL REQUIREMENTS:
 MICROSECTION: YES
 BARE BOARD ELEC. TEST: NONE REQUIRED PER ORDER
 XX MIL VAS REQUIRE NON-CONDUCTIVE FILL AND PLANARIZE
 XX MIL VAS REQUIRE CONDUCTIVE FILL AND PLANARIZE
 OUTER 10.25MIL TRACES REQUIRE 50 OHM SINGLE-ENDED IMPEDANCE
 LAYER 2 & 3 (INNER LAYERS) XX MIL WIDE, XX MIL SPACE
 TRACES REQUIRE 100 OHM DIFFERENTIAL IMPEDANCE

PROJECT TITLE: M2-CC3351
DESIGNED FOR Public Release

FILE NAME: MCU127_M2-CC3351_RevA.PcbDoc

ENGINEER: Jessica M. Torres
LAYOUT BY: Jessica M. Torres

SCALE: 1.00
ALTIM DESIGNER VERSION: 24.2.2.26